
RTG4 DDR Memory Controller with Initialization

Configuration User Guide



a  MICROCHIP company

Revision History

Revision 2.0

Updated the contact information and added this revision history.

Revision 1.0

First publication of this document.

Table of Contents

Introduction	3
1 – Fabric External Memory DDRController Configurator.....	4
Memory Settings.....	4
Fabric Interface Settings.....	5
IO Drive Strength (DDR2 and DDR3 only).....	5
IO Standard (LPDDR only)	5
IO Calibration.....	6
Enable Interrupts.....	6
Fabric Clock Frequency.....	6
Memory Bandwidth.....	6
Total Bandwidth.....	6
2 – FDDR Controller Configuration	7
Fabric DDR Control Registers.....	7
Fabric DDR Registers Configuration.....	7
Importing DDR Configuration Files.....	9
Exporting DDR Configuration Files.....	10
Generated Data.....	10
3 – FDDR component with built-in initialization	11
Initialization.....	11
CoreABC FDDR initialization sequence file.....	11
Converting the RTG4FDDRC_INIT component to SmartDesign	11
CoreABC Program	13
4 – Port Description.....	14
FDDR Core Ports	14
Interrupt Ports.....	14
APB3 Configuration Interface.....	14
DDR PHY Interface	15
AXI Bus Interface.....	16
AHB0 Bus Interface.....	17
AHB1 Bus Interface.....	18
A –Product Support.....	19
Customer Service.....	19
ITAR Technical Support.....	20

Introduction

The RTG4 FPGA has two DDR memory controller blocks located on the East and West side of the chip identified as:

- East FDDR
- West FDDR

The DDR controllers control off-chip DDR memories.

To fully configure the RTG4 DDR memory controller you must:

1. Use the RTG4 DDR Memory Controller Configurator to configure the DDR Controller, select its datapath bus interface (AXI or AHB), and select the DDR clock frequency as well as the fabric datapath clock frequency.
2. Set the register values for the DDR controller registers to match your external DDR memory characteristics.
3. Instantiate the DDR controller as part of a user application and make datapath connections.
4. Connect the DDR controller's APB configuration interface as defined by the Peripheral Initialization solution.

1 – Fabric External Memory DDR Controller Configurator

The Fabric External Memory DDR (FDDR) Configurator is used to configure the overall datapath and the external DDR memory parameters for the Fabric DDR Controller.

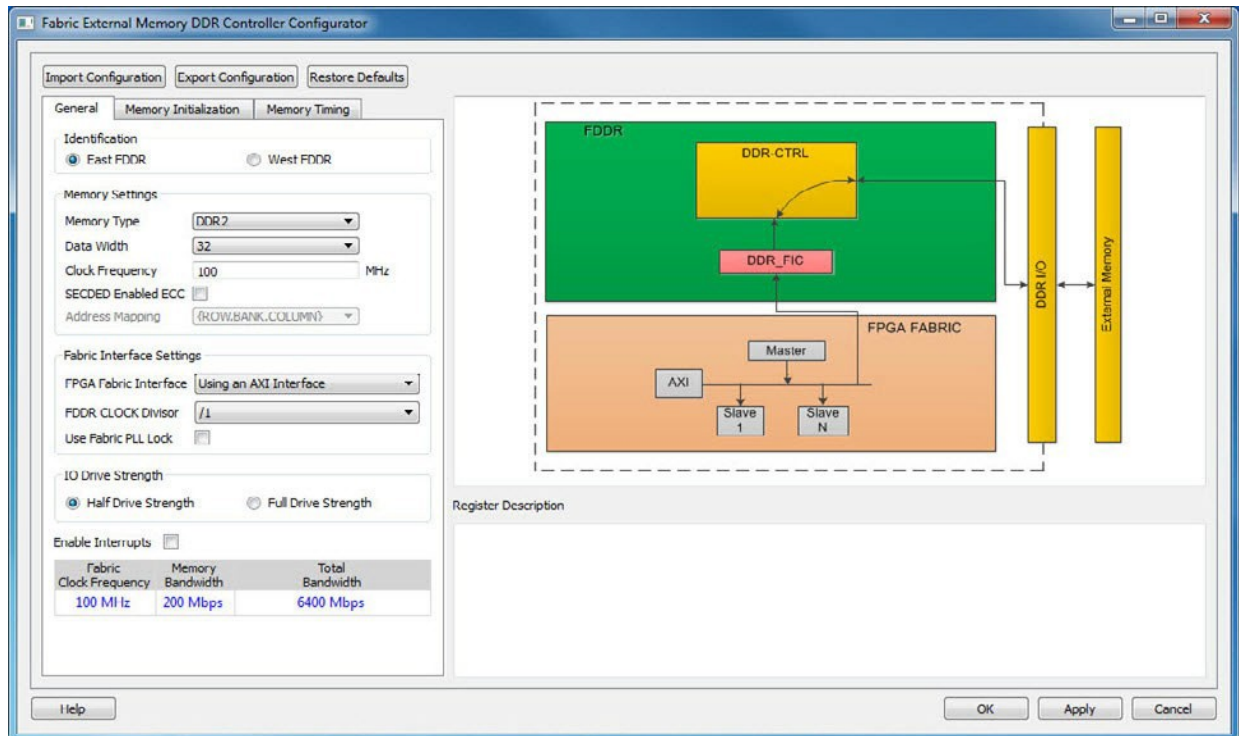


Figure 1-1 • FDDR Configurator Overview

Memory Settings

Use Memory Settings to configure your memory options in the MDDR.

- **Memory Type** - LPDDR, DDR2, or DDR3
- **Data Width** - 32-bit, 16-bit or 8-bit
- **Clock Frequency** - Any value (Decimal/Fractional) in the range of 20 MHz to 333MHz
- **SECEDED Enabled ECC** - ON or OFF
Single Error Correction Double Error Detection (SECEDED) ECC feature of DDR/LPDDR.

Fabric Interface Settings

FPGA Fabric Interface - This is the data interface between the FDDR and the FPGA design. Since the FDDR is a memory controller, it is intended to be a slave on an AXI or AHB bus. The Master of the bus initiates bus transactions, which are in turn interpreted by the FDDR as memory transactions and communicated to the off-chip DDR Memory. FDDR fabric interface options are:

- **Using an AXI Interface** - one master accesses the FDDR through a 64-bit AXI interface.
- **Using a Single AHB Interface** - one master accesses the FDDR through a single 32-bit AHB interface.
- **Using Two AHB Interfaces** - two masters can access the FDDR using two 32-bit AHB interfaces.

FPGA CLOCK Divisor - specifies the frequency ratio between the DDR Controller clock (CLK_FDDR) and the clock controlling the fabric interface (CLK_FIC64). The CLK_FIC64 frequency should be equal to that of the AHB/AXI subsystem that is connected to the FDDR AHB/AXI bus interface. For example, if you have a DDR RAM running at 200 MHz and your Fabric/AXI Subsystem runs at 100 MHz you must select a divisor of 2 (Figure 1-2).

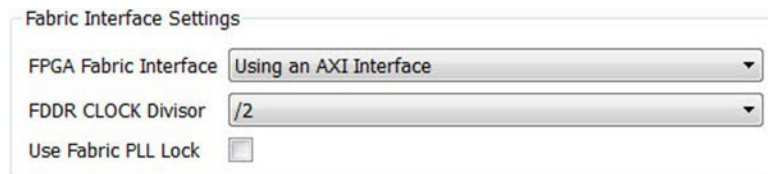


Figure 1-2 • Fabric Interface Settings - AXI Interface and FDDR Clock Divisor Agreement

Use Fabric PLL LOCK - when CLK_BASE is sourced from a Fabric CC,C you can connect the fabric CCC LOCK output to the FDDR FAB_PLL_LOCK input. CLK_BASE is not stable until the Fabric CCC locks. Therefore, Microsemi recommends that you hold the FDDR in reset (i.e., assert the CORE_RESET_N input) until CLK_BASE is stable. The LOCK output of the Fabric CCC indicates that the Fabric CCC output clocks are stable. By checking the **Use FAB_PLL_LOCK** option, you can expose the FAB_PLL_LOCK input port of the FDDR. You can then connect the LOCK output of the Fabric CCC to the FAB_PLL_LOCK input of the FDDR.

IO Drive Strength (DDR2 and DDR3 only)

Select one of the following drive strengths for your DDR I/Os:

- Half Drive Strength
- Full Drive Strength

Depending on your DDR Memory type and the I/O Strength you select, Libero SoC sets the DDR I/O Standard for your FDDR system as follows:

DDR Memory Type	Half Drive Strength	Full Drive Strength
DDR3	SSTL15I	SSTL15II
DDR2	SSTL18I	SSTL18II

IO Standard (LPDDR only)

Select one of the following options:

- LVCMOS18 (Lowest Power) for LVCMOS 1.8V IO standard.
- LPDDR1 Note: Before you choose this standard, make sure that your board supports this standard.

IO Calibration

Choose one of the following options:

- On
- Off

Calibration ON and OFF provide different values for PCODE and NCODE registers. The I/O calibration block calibrates the I/O drivers to an external resistor. The impedance control is used to identify the digital values PCODE<5:0> and NCODE<5:0>. These values are fed to the pull-up/pull-down reference network to match the impedance with an external resistor. Once it matches the PCODE and NCODE registers, they are latched and sent to the drivers. Users turn on or turn off this feature as per their board requirements.

Enable Interrupts

The FDDR is capable of raising interrupts when certain predefined conditions are satisfied. Check **Enable Interrupts** in the FDDR configurator if you would like to use these interrupts in your application. This exposes the interrupt signals on the FDDR instance. You can connect these interrupt signals as your design requires. The following Interrupt signals and their preconditions are available:

- **FIC_INT** - generated when there is an error in the transaction between the Master and the FDDR.
- **IO_CAL_INT** - enables you to recalibrate DDR I/O's by writing to DDR controller registers via the APB configuration interface. When calibration is complete, this interrupt is raised. For details about I/O recalibration, refer to the Microsemi RTG4 User's Guide.
- **PLL_LOCK_INT** - indicates that the FDDR FPLL has locked.
- **PLL_LOCKLOST_INT** - indicates that the FDDR FPLL has lost lock.
- **FDDR_ECC_INT** - indicates a single or two-bit error has been detected.

Fabric Clock Frequency

Clock frequency (CLK_BASE) calculation based on your current DDR Controller Clock (CLK_FDDR) frequency and the FDDR CLOCK divisor, displayed in MHz.

Fabric Clock (CLK_BASE) Frequency (in MHz) = CLK_FDDR Clock Frequency / FDDR CLOCK divisor

Memory Bandwidth

Memory bandwidth calculation based on your current Clock Frequency value in Mbps.

Memory Bandwidth (in Mbps) = 2 * Clock Frequency

Total Bandwidth

Total bandwidth calculation based on your current Fabric Clock Frequency (CLK_BASE), DDR, Data Width and FDDR CLOCK divisor, in Mbps.

Total Bandwidth (in Mbps) = (2 * Fabric Clock Frequency * DDR Data Width) / FDDR CLOCK Divisor

2 – FDDR Controller Configuration

When you use the Fabric DDR Controller to access an external DDR Memory, the DDR Controller must be configured at runtime. This is done by writing configuration data to dedicated DDR controller configuration registers. This configuration data is dependent on the characteristics of the external DDR memory and your application. This section describes how to enter these configuration parameters in the FDDR controller configurator and how to build the initialization circuitry for the FDDR Controller after the FDDR controller is configured.

Fabric DDR Control Registers

The Fabric DDR Controller has a set of registers that need to be configured at runtime. The configuration values for these registers represent different parameters (for example, DDR mode, PHY width, burst mode, ECC, etc.). For details about the DDR controller configuration registers, refer to the Microsemi RTG4 User's Guide.

Fabric DDR Registers Configuration

Use the Memory Initialization ([Figure 2-1](#)) and Memory Timing ([Figure 2-2](#)) tabs to enter parameters that correspond to your DDR Memory and application. Consult your DDR Memory vendor's datasheet for values to enter in these two tabs.

Values you enter in these tabs are automatically translated to the appropriate register values. When you click a specific parameter its corresponding register is described in the Register Description Window ([Figure 1-1 on page 4](#)).

General	Memory Initialization	Memory Timing
Burst Length	4	Bits
Burst Order	Sequential	
Timing Mode	1T	
CAS Latency	5	Clks
Self Refresh Enabled	NO	Bursts
Auto Refresh Burst Count	Single	
Powerdown Enabled	YES	
Stop the Clock	NO	
Deep Powerdown Enabled	NO	
Powerdown Entry Time	192	
Additive CAS Latency	0	Clks
CAS Write Latency	5	Clks
Zqinit	0	Clks
ZQCS	0	Clks
ZQCS Interval	0	Clks

Figure 2-1 • FDDR Configuration - Memory Initialization Tab

General	Memory Initialization	Memory Timing
		Time to Hold Reset before INIT <input type="text" value="0"/> Clks
		MRD <input type="text" value="0"/> Clks
		RAS (Min) <input type="text" value="0"/> Clks
		RAS (Max) <input type="text" value="1024"/> Clks
		RCD <input type="text" value="0"/> Clks
		RP <input type="text" value="0"/> Clks
		REFI <input type="text" value="2624"/> Clks
		RC <input type="text" value="0"/> Clks
		XP <input type="text" value="0"/> Clks
		CKE <input type="text" value="0"/> Clks
		RFC <input type="text" value="35"/> Clks
		WR <input type="text" value="5"/> Clks
		FAW <input type="text" value="0"/> Clks

Figure 2-2 • FDDR Configuration - Memory Timing Tab

Importing DDR Configuration Files

In addition to entering DDR Memory parameters using the Memory Initialization and Timing tabs, you can import DDR register values from a file. To do so, click the **Import Configuration** button and navigate to the text file containing DDR register names and values. [Figure 2-3](#) shows the import configuration syntax.

```
ddrc_dyn_soft_reset_CR      0x00 ;
ddrc_dyn_refresh_1_CR      0x27DE ;
ddrc_dyn_refresh_2_CR      0x030F ;
ddrc_dyn_powerdown_CR      0x02 ;
ddrc_dyn_debug_CR          0x00 ;
ddrc_ecc_data_mask_CR      0x0000 ;
ddrc_addr_map_col_1_CR     0x3333 ;
ddrc_addr_map_col_3_CR     0x3300 ;
ddrc_init_1_CR             0x0001 ;
ddrc_cke_rstn_cycles_CR1   0x0100 ;
ddrc_cke_rstn_cycles_CR2   0x0008 ;
ddrc_init_emr2_CR          0x0000 ;
ddrc_init_emr3_CR          0x0000 ;
ddrc_dram_bank_act_timing CR 0x1947;
```

Figure 2-3 • DDR Register Configuration File Syntax

Note: If you import register values rather than entering them using the GUI, you must specify all necessary register values. Consult the SmartFusion2 User Guide for details.

Exporting DDR Configuration Files

You can also export the current register configuration data into a text file. This file will contain register values that you imported (if any) as well as those that were computed from GUI parameters you entered in this dialog. If you want to undo changes you have made to the DDR register configuration, you can do so with Restore Default. This deletes all register configuration data and you must either re-import or reenter this data. The data is reset to the hardware reset values.

Generated Data

Click **OK** to generate the configuration. Based on your input in the General, Memory Timing and Memory Initialization tabs, the FDDR Configurator computes values for all DDR configuration registers and exports these values into your firmware project and simulation files. The exported file syntax is shown in Figure 2-4.

```
# Exported: 2013-Sep-02 05:07:16
# Libero DDR Configurator GUI Version = 2.0
# DDR Controller Type = DDR2
# Bus Width = 32-bits
# Memory Bandwidth = 200 Mbps
# Total Bandwidth = 6400 Mbps
#
# Validation Status:
# Target Device Manufacturer:
# Target Device:
#
# User Comments:
#
#
DDRC_ADDR_MAP_BANK_CR.REG_DDRC_ADDRMAP_BANK_B2      0xa
DDRC_ADDR_MAP_BANK_CR.REG_DDRC_ADDRMAP_BANK_B1      0xa
DDRC_ADDR_MAP_BANK_CR.REG_DDRC_ADDRMAP_BANK_B0      0xa
DDRC_ADDR_MAP_COL_1_CR.REG_DDRC_ADDRMAP_COL_B7      0x3
DDRC_ADDR_MAP_COL_1_CR.REG_DDRC_ADDRMAP_COL_B4      0x3
DDRC_ADDR_MAP_COL_1_CR.REG_DDRC_ADDRMAP_COL_B3      0x3
DDRC_ADDR_MAP_COL_1_CR.REG_DDRC_ADDRMAP_COL_B2      0x3
DDRC_ADDR_MAP_COL_2_CR.REG_DDRC_ADDRMAP_COL_B11     0xf
DDRC_ADDR_MAP_COL_2_CR.REG_DDRC_ADDRMAP_COL_B10     0xf
DDRC_ADDR_MAP_COL_2_CR.REG_DDRC_ADDRMAP_COL_B9      0xf
DDRC_ADDR_MAP_COL_2_CR.REG_DDRC_ADDRMAP_COL_B8      0x3
DDRC_ADDR_MAP_COL_3_CR.REG_DDRC_ADDRMAP_COL_B6      0x3
DDRC_ADDR_MAP_COL_3_CR.REG_DDRC_ADDRMAP_COL_B5      0x3
```

Figure 2-4 • Exported DDR Register Configuration File Syntax

3 – FDDR component with built-in initialization

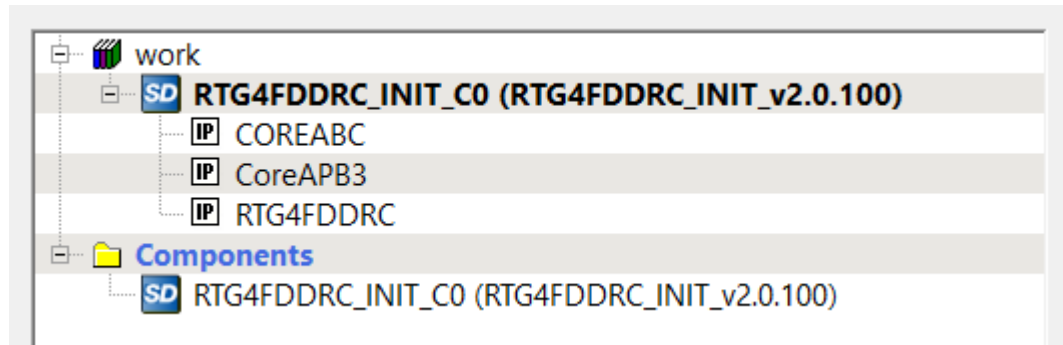


Figure 3-1 • Expanded module hierarchy of FDDR component with built-in initialization

Initialization

This core has a built-in initialization state machine. Upon the assertion/de-assertion of the INIT_RESET_N (Active Low) signal, the FDDR block is initialized with the user configurations. When the configuration phase is complete, the INIT_DONE signal is asserted and the FDDR block is ready for normal operations.

Note: The clock used for initialization should be a 50MHz clock connected to the INIT_CLK_50MHz signal.

You can have the FDDR initialization start automatically at power up by connecting the INIT_RESET_N (Active Low) input of the FDDR block to the POWER_ON_RESET_N (Active Low) signal of the SYSRESET macro.

CoreABC FDDR initialization sequence file:

When the FDDR component with built-in initialization is generated, CoreABC is automatically configured with the initialization sequence/program that has instructions to configure DDR registers and initialize the FDDR. Mentioned below are some of the various steps that the CoreABC program performs:

- Conduct the FPLL calibration/workaround, which includes polling for the FPLL_LOCK output from FDDR.
- Configure the DDR registers.
- Wait for controller ready and memory settling time, and then assert INIT_DONE.

The same CoreABC program is also generated to an instruction text file `fdcr_init_abc_file.txt` that can be found at `<project_name>\component\work\RTG4FDDRC_INIT_C0\FDDRC_0`. You can refer to this file to review the instructions and detailed comments. In order to correlate the changes in the CoreABC program into the generated HDL, the resulting `instructions.v` file can be found at `<project_name>\component\work\RTG4FDDRC_INIT_C0\COREABC_0\rtl\vlog\core`.

Converting the RTG4FDDRC_INIT component to SmartDesign:

To convert the FDDR component with built-in initialization into a regular SmartDesign component, right click the component in Design Hierarchy and select **Convert to SmartDesign**.

Note: Any changes made in this SmartDesign component are lost when converting back to original IP component.

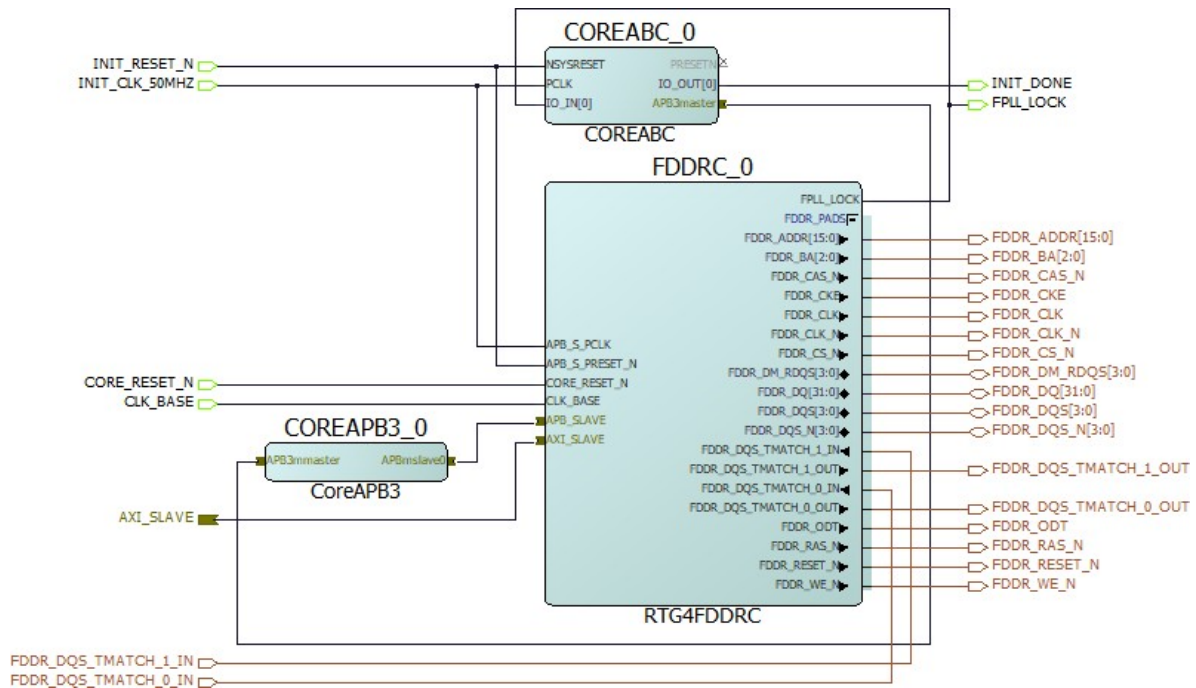
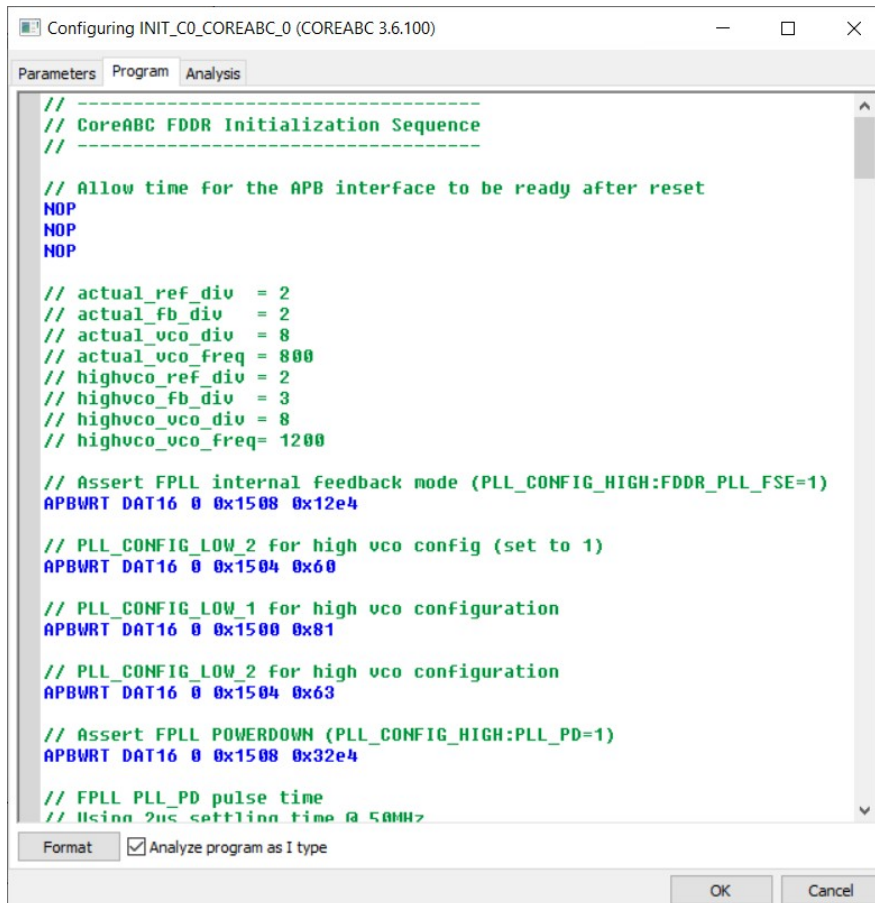


Figure 3-2 • FDDR component with built-in initialization as a regular SmartDesign

CoreABC Program:

The CoreABC program can be seen by opening the CoreABC configurator and selecting the Program Tab. You may choose to modify the program/sequence as per your requirement.



```

// -----
// CoreABC FDDR Initialization Sequence
// -----

// Allow time for the APB interface to be ready after reset
NOP
NOP
NOP

// actual_ref_div = 2
// actual_fb_div = 2
// actual_vco_div = 8
// actual_vco_freq = 800
// highvco_ref_div = 2
// highvco_fb_div = 3
// highvco_vco_div = 8
// highvco_vco_freq= 1200

// Assert FPLL internal feedback mode (PLL_CONFIG_HIGH:FDDR_PLL_FSE=1)
APBWRT DAT16 0 0x1508 0x12e4

// PLL_CONFIG_LOW_2 for high vco config (set to 1)
APBWRT DAT16 0 0x1504 0x60

// PLL_CONFIG_LOW_1 for high vco configuration
APBWRT DAT16 0 0x1500 0x81

// PLL_CONFIG_LOW_2 for high vco configuration
APBWRT DAT16 0 0x1504 0x63

// Assert FPLL POWERDOWN (PLL_CONFIG_HIGH:PLL_PD=1)
APBWRT DAT16 0 0x1508 0x32e4

// FPLL PLL_PD pulse time
// Using 2us settling time @ 50MHz

```

Format Analyze program as I type

OK Cancel

Figure 3-3 • CoreABC Program

4 – Port Description

FDDR Core Ports

Table 4-1 • FDDR Core Ports

Port Name	Direction	Description
CORE_RESET_N	IN	FDDR Controller Reset
CLK_BASE	IN	FDDR Fabric Interface Clock
INIT_CLK_50MHZ	IN	Initialization clock. Must be connected to a 50MHz clock source
INIT_RESET_N	IN	Active Low signal. Assert/de-assert this signal to start the initialization of the FDDR
INIT_DONE	OUT	Asserted high when the initialization of the FDDR block is complete

Interrupt Ports

This group of ports is exposed when you select the Enable Interrupts option.

Table 4-2 • Interrupt Ports

Port Name	Direction	Description
PLL_LOCK_INT	OUT	Asserts when FDDR PLL locks
PLL_LOCKLOST_INT	OUT	Asserts when FDDR PLL lock is lost
ECC_INT	OUT	Asserts when an ECC Event occurs
IO_CALIB_INT	OUT	Asserts when I/O calibration is complete
FIC_INT	OUT	Asserts when there is an error in the AHB/AXI protocol on the Fabric interface

APB3 Configuration Interface

Table 4-3 • APB3 Configuration Interface

Port Name	Direction	Description
APB_S_PENABLE	IN	Slave Enable
APB_S_PSEL	IN	Slave Select
APB_S_PWRITE	IN	Write Enable
APB_S_PADDR[10:2]	IN	Address
APB_S_PWDATA[15:0]	IN	Write Data
APB_S_PREADY	OUT	Slave Ready
APB_S_PSLVERR	OUT	Slave Error
APB_S_PRDATA[15:0]	OUT	Read Data
APB_S_PRESET_N	IN	Slave Reset
APB_S_PCLK	IN	Clock

DDR PHY Interface

Table 4-4 • DDR PHY Interface

Port Name	Direction	Description
FDDR_CAS_N	OUT	DRAM CASN
FDDR_CKE	OUT	DRAM CKE
FDDR_CLK	OUT	Clock, P side
FDDR_CLK_N	OUT	Clock, N side
FDDR_CS_N	OUT	DRAM CSN
FDDR_ODT	OUT	DRAM ODT
FDDR_RAS_N	OUT	DRAM RASN
FDDR_RESET_N	OUT	DRAM Reset for DDR3
FDDR_WE_N	OUT	DRAM WEN
FDDR_ADDR[15:0]	OUT	Dram Address bits
FDDR_BA[2:0]	OUT	Dram Bank Address
FDDR_DM_RDQS[4:0]	INOUT	Dram Data Mask
FDDR_DQS[4:0]	INOUT	Dram Data Strobe Input/Output - P Side
FDDR_DQS_N[4:0]	INOUT	Dram Data Strobe Input/Output - N Side
FDDR_DQ[35:0]	INOUT	DRAM Data Input/Output
FDDR_FIFO_WE_IN[2:0]	IN	FIFO in signal
FDDR_FIFO_WE_OUT[2:0]	OUT	FIFO out signal
FDDR_DM_RDQS ([3:0]/[1:0]/[0])	INOUT	Dram Data Mask
FDDR_DQS ([3:0]/[1:0]/[0])	INOUT	Dram Data Strobe Input/Output - P Side
FDDR_DQS_N ([3:0]/[1:0]/[0])	INOUT	Dram Data Strobe Input/Output - N Side
FDDR_DQ ([31:0]/[15:0]/[7:0])	INOUT	DRAM Data Input/Output
FDDR_DQS_TMATCH_0_IN	IN	FIFO in signal
FDDR_DQS_TMATCH_0_OUT	OUT	FIFO out signal
FDDR_DQS_TMATCH_1_IN	IN	FIFO in signal (32-bit only)
FDDR_DQS_TMATCH_1_OUT	OUT	FIFO out signal (32-bit only)
FDDR_DM_RDQS_ECC	INOUT	Dram ECC Data Mask
FDDR_DQS_ECC	INOUT	Dram ECC Data Strobe Input/Output - P Side
FDDR_DQS_ECC_N	INOUT	Dram ECC Data Strobe Input/Output - N Side
FDDR_DQ_ECC ([3:0]/[1:0]/[0])	INOUT	DRAM ECC Data Input/Output
FDDR_DQS_TMATCH_ECC_IN	IN	ECC FIFO in signal
FDDR_DQS_TMATCH_ECC_OUT	OUT	ECC FIFO out signal (32-bit only)

Note: Port widths for some ports change depending on the selection of the PHY width. The notation "[a:0]/[b:0]/[c:0]" is used to denote such ports, where "[a:0]" refers to the port width when a 32-bit PHY width is selected, "[b:0]" corresponds to a 16-bit PHY width, and "[c:0]" corresponds to an 8-bit PHY width.

AXI Bus Interface

Table 4-5 • AXI Bus Interface

Port Name	Direction	Description
AXI_S_AWREADY	OUT	Write address ready
AXI_S_WREADY	OUT	Write address ready
AXI_S_BID[3:0]	OUT	Response ID
AXI_S_BRESP[1:0]	OUT	Write response
AXI_S_BVALID	OUT	Write response valid
AXI_S_ARREADY	OUT	Read address ready
AXI_S_RID[3:0]	OUT	Read ID Tag
AXI_S_RRESP[1:0]	OUT	Read Response
AXI_S_RDATA[63:0]	OUT	Read data
AXI_S_RLAST	OUT	Read Last This signal indicates the last transfer in a read burst
AXI_S_RVALID	OUT	Read address valid
AXI_S_AWID[3:0]	IN	Write Address ID
AXI_S_AWADDR[31:0]	IN	Write address
AXI_S_AWLEN[3:0]	IN	Burst length
AXI_S_AWSIZE[1:0]	IN	Burst size
AXI_S_AWBURST[1:0]	IN	Burst type
AXI_S_AWLOCK[1:0]	IN	Lock type This signal provides additional information about the atomic characteristics of the transfer
AXI_S_AWVALID	IN	Write address valid
AXI_S_WID[3:0]	IN	Write Data ID tag
AXI_S_WDATA[63:0]	IN	Write data
AXI_S_WSTRB[7:0]	IN	Write strobes
AXI_S_WLAST	IN	Write last
AXI_S_WVALID	IN	Write valid
AXI_S_BREADY	IN	Write ready
AXI_S_ARID[3:0]	IN	Read Address ID
AXI_S_ARADDR[31:0]	IN	Read address
AXI_S_ARLEN[3:0]	IN	Burst length
AXI_S_ARSIZE[1:0]	IN	Burst size
AXI_S_ARBURST[1:0]	IN	Burst type
AXI_S_ARLOCK[1:0]	IN	Lock Type
AXI_S_ARVALID	IN	Read address valid
AXI_S_RREADY	IN	Read address ready
AXI_S_CORE_RESET_N	IN	FDDR Global Reset

AHB0 Bus Interface

Table 4-6 • AHB0 Bus Interface

Port Name	Direction	Description
AHB0_S_HREADYOUT	OUT	AHBL slave ready - When high for a write indicates the slave is ready to accept data and when high for a read indicates that data is valid.
AHB0_S_HRESP	OUT	AHBL response status - When driven high at the end of a transaction indicates that the transaction has completed with errors. When driven low at the end of a transaction indicates that the transaction has completed successfully.
AHB0_S_HRDATA[31:0]	OUT	AHBL read data - Read data from the slave to the master
AHB0_S_HSEL	IN	AHBL slave select - When asserted, the slave is the currently selected AHBL slave on the AHB bus
AHB0_S_HADDR[31:0]	IN	AHBL address - byte address on the AHBL interface
AHB0_S_HBURST[2:0]	IN	AHBL Burst Length
AHB0_S_HSIZE[1:0]	IN	AHBL transfer size - Indicates the size of the current transfer (8/16/32 byte transactions only)
AHB0_S_HTRANS[1:0]	IN	AHBL transfer type - Indicates the transfer type of the current transaction.
AHB0_S_HMASTLOCK	IN	AHBL lock - When asserted the current transfer is part of a locked transaction.
AHB0_S_HWRITE	IN	AHBL write - When high indicates that the current transaction is a write. When low indicates that the current transaction is a read.
AHB0_S_HREADY	IN	AHBL ready - When high, indicates that the slave is ready to accept a new transaction.
AHB0_S_HWDATA[31:0]	IN	AHBL write data - Write data from the master to the slave

AHB1 Bus Interface

Table 4-7 • AHB1 Bus Interface

Port Name	Direction	Description
AHB1_S_HREADYOUT	OUT	AHBL slave ready - When high for a write indicates the slave is ready to accept data and when high for a read indicates that data is valid.
AHB1_S_HRESP	OUT	AHBL response status - When driven high at the end of a transaction indicates that the transaction has completed with errors. When driven low at the end of a transaction indicates that the transaction has completed successfully.
AHB1_S_HRDATA[31:0]	OUT	AHBL read data - Read data from the slave to the master
AHB1_S_HSEL	IN	AHBL slave select - When asserted, the slave is the currently selected AHBL slave on the AHB bus
AHB1_S_HADDR[31:0]	IN	AHBL address - byte address on the AHBL interface
AHB1_S_HBURST[2:0]	IN	AHBL Burst Length
AHB1_S_HSIZE[1:0]	IN	AHBL transfer size - Indicates the size of the current transfer (8/16/32 byte transactions only)
AHB1_S_HTRANS[1:0]	IN	AHBL transfer type - Indicates the transfer type of the current transaction.
AHB1_S_HMASTLOCK	IN	AHBL lock - When asserted the current transfer is part of a locked transaction.
AHB1_S_HWRITE	IN	AHBL write - When high indicates that the current transaction is a write. When low indicates that the current transaction is a read.
AHB1_S_HREADY	IN	AHBL ready - When high, indicates that the slave is ready to accept a new transaction.
AHB1_S_HWDATA[31:0]	IN	AHBL write data - Write data from the master to the slave

A – Product Support

Microsemi SoC Products Group backs its products with various support services, including Customer Service, Customer Technical Support Center, a website, electronic mail, and worldwide sales offices. This appendix contains information about contacting Microsemi SoC Products Group and using these support services.

Customer Service

Contact Customer Service for non-technical product support, such as product pricing, product upgrades, update information, order status, and authorization.

From North America, call 800.262.1060

From the rest of the world, call 650.318.4460

Fax, from anywhere in the world, 408.643.6913

Customer Technical Support Center

Microsemi SoC Products Group staffs its Customer Technical Support Center with highly skilled engineers who can help answer your hardware, software, and design questions about Microsemi SoC Products. The Customer Technical Support Center spends a great deal of time creating application notes, answers to common design cycle questions, documentation of known issues, and various FAQs. So, before you contact us, please visit our online resources. It is very likely we have already answered your questions.

Technical Support

For Microsemi SoC Products Support, visit <http://www.microsemi.com/products/fpga-soc/design-support/fpga-soc-support>.

Website

You can browse a variety of technical and non-technical information on the Microsemi SoC Products Group home page, at www.microsemi.com/soc.

Contacting the Customer Technical Support Center

Highly skilled engineers staff the Technical Support Center. The Technical Support Center can be contacted by email or through the Microsemi SoC Products Group website.

Email

You can communicate your technical questions through our Web portal and receive answers back by email, fax, or phone. Also, if you have design problems, you can upload your design files to receive assistance. We constantly monitor the cases created from the web portal throughout the day. When sending your request to us, please be sure to include your full name, company name, and your contact information for efficient processing of your request.

Technical support can be reached at <https://soc.microsemi.com/Portal/Default.aspx>.

For technical support on RH and RT FPGAs that are regulated by International Traffic in Arms Regulations (ITAR), log in at <https://soc.microsemi.com/Portal/Default.aspx>, go to the My Cases tab, and select Yes in the ITAR drop-down list when creating a new case. For a complete list of ITAR-regulated Microsemi FPGAs, visit the ITAR web page.

My Cases

Microsemi SoC Products Group customers may submit and track technical cases online by going to [My Cases](#).

Outside the U.S.

Customers needing assistance outside the US time zones can either contact technical support at <https://soc.microsemi.com/Portal/Default.aspx> or contact a local sales office.

Visit [About Us](#) for sales office listings and corporate contacts.

Sales office listings can be found at www.microsemi.com/soc/company/contact/default.aspx.



Microsemi Corporate Headquarters
One Enterprise, Aliso Viejo,
CA 92656 USA

Within the USA: +1 (800) 713-4113
Outside the USA: +1 (949) 380-6100
Sales: +1 (949) 380-6136
Fax: +1 (949) 215-4996

E-mail: sales.support@microsemi.com

©2015 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for communications, defense and security, aerospace, and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs, and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; security technologies and scalable anti-tamper products; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, Calif. and has approximately 3,400 employees globally. Learn more at www.microsemi.com.

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.